

SMD ▪ Mini Top View LEDs 65-11-BLP-1CS1T2A7C-2T8-AM



Features

- P-LCC-2 package.
- Colored diffused resin.
- Wide viewing angle 120°.
- Inner reflector and white package.
- Brightness: 180 to 450mcd at 10mA
- Precondition: Bases on JEDEC J-STD 020D Level 2
- Qualification according to AEC-Q101 rev C.
- Automotive reflow profile (IR reflow or wave soldering)

Applications

- Automotive backlighting or indicator: Dashboard, switch, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- Optical indicator.

Device Selection Guide

| Chip Materials | Emitted Color | Resin Color |
|----------------|---------------|-----------------------|
| InGaN | Sky Blue | Slightly green dotted |

Absolute Maximum Ratings (Ta=25°C)

| Parameter | Symbol | Rating | Unit |
|-------------------------------------------|---------------|-----------------------------------------------------------------------------|------|
| Reverse Voltage | V_R | 5 | V |
| Forward Current | I_F | 30 | mA |
| Peak Forward Current (Duty 1/10 @1KHz) | I_{FP} | 100 | mA |
| Power Dissipation | P_d | 95 | mW |
| Junction Temperature | T_j | 125 | °C |
| Operating Temperature | T_{opr} | -40 ~ +100 | °C |
| Storage Temperature | T_{stg} | -40 ~ +110 | °C |
| Thermal Resistance | $R_{th\ J-A}$ | 600 | K/W |
| | $R_{th\ J-S}$ | 400 | K/W |
| ESD (Classification acc. AEC Q101) | ESD_{HBM} | 2000 | V |
| | ESD_{MM} | 200 | V |
| Soldering Temperature | T_{sol} | Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec. | |

Electro-Optical Characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|--------------------|-------------------|-------|-------|-------|------|----------------------|
| Luminous Intensity | I _v | 180 | ----- | 450 | mcd | I _F =10mA |
| Viewing Angle | 2θ _{1/2} | ----- | 120 | ----- | deg | I _F =10mA |
| Forward Voltage | V _F | 2.7 | ---- | 3.8 | V | I _F =10mA |
| Reverse Current | I _R | ----- | ----- | 10 | μA | V _R =5V |

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

| Bin Code | Min. | Max. | Unit | Condition |
|----------|------|------|------|----------------------|
| S1 | 180 | 224 | mcd | I _F =10mA |
| S2 | 224 | 280 | | |
| T1 | 280 | 355 | | |
| T2 | 355 | 450 | | |

Note:

Tolerance of Luminous Intensity: ±11%

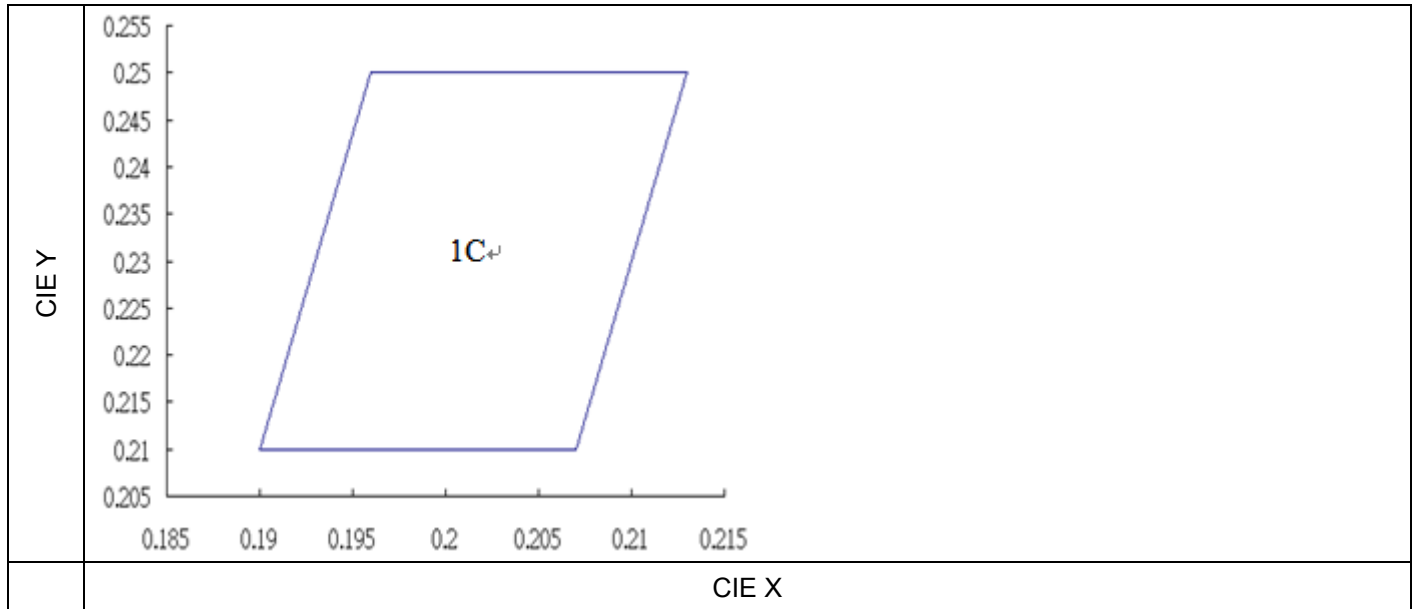
Bin Range of Chromaticity Coordinates Specifications

| Bin Code | CIE x | CIE y | Condition |
|----------|-------|-------|----------------------|
| 1C | 0.190 | 0.210 | I _F =10mA |
| | 0.207 | 0.210 | |
| | 0.213 | 0.250 | |
| | 0.196 | 0.250 | |

Note:

Tolerance of Chromaticity Coordinates: ±0.01

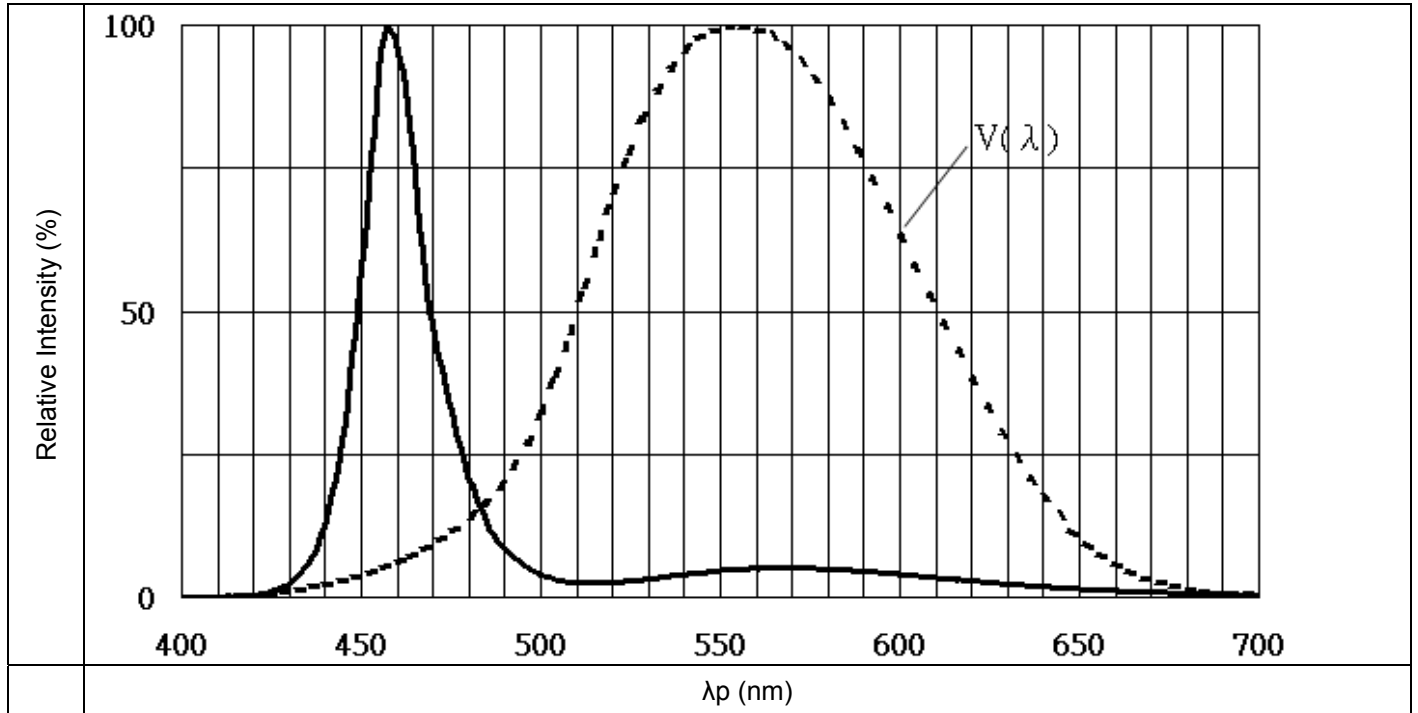
The C.I.E. 1931 Chromaticity Diagram



Note:
Tolerance of Chromaticity Coordinates: ± 0.01

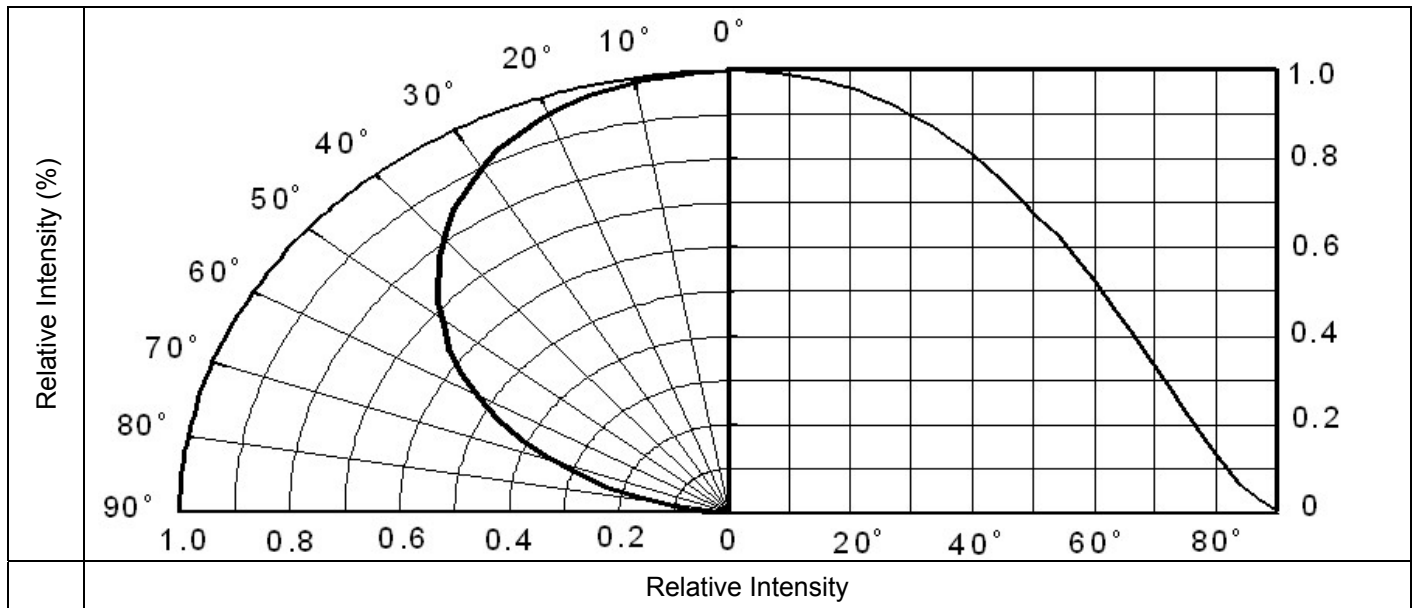
Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution

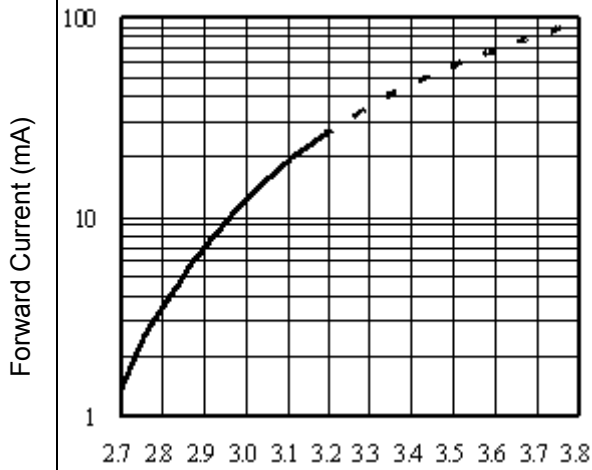


Note: $V(\lambda)$ =Standard eye response curve; $I_F = 10\text{mA}$

Diagram Characteristics of Radiation

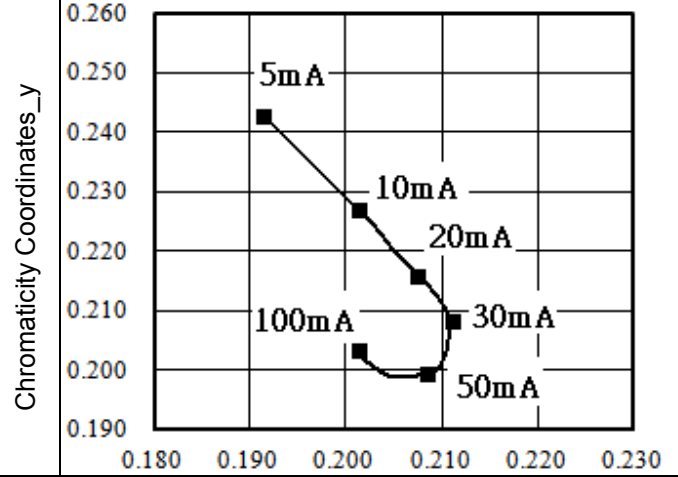


Forward Current vs. Forward Voltage (Ta=25°C)



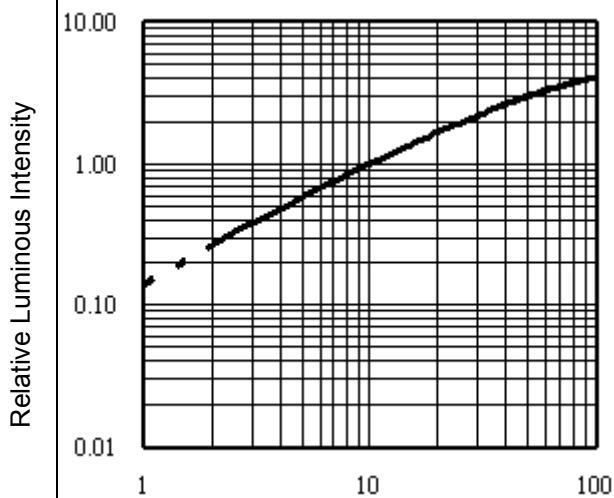
Forward Voltage (V)

Chromaticity Coordinates vs. Forward Current (Ta=25°C)



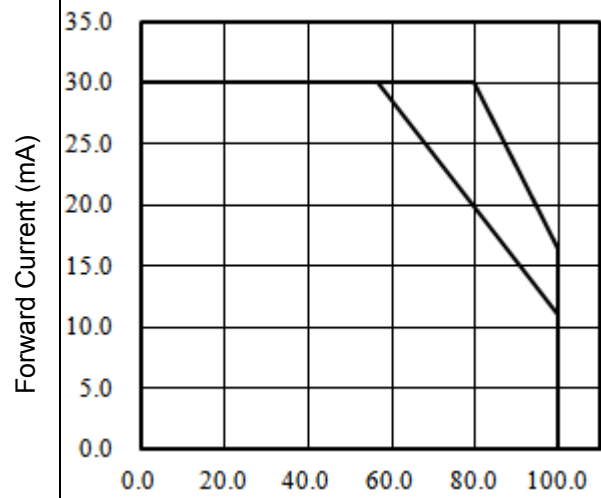
Chromaticity Coordinates_x

Relative Luminous Intensity vs. Forward Current (Ta=25°C)



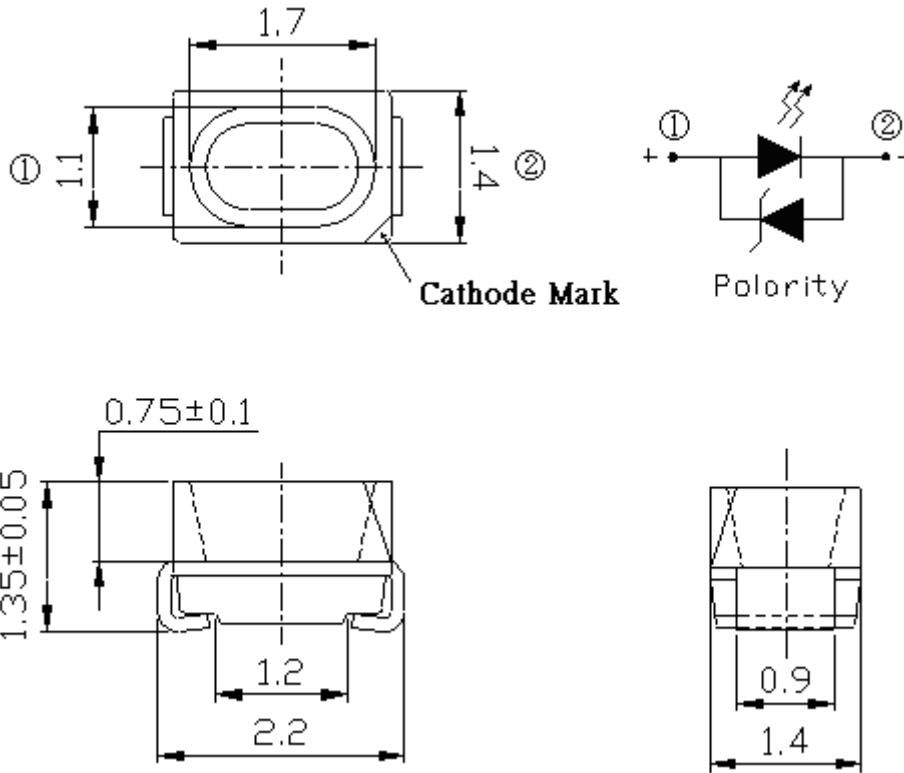
Forward Current (mA)

Max. Permissible Forwarded Current(Ta=25°C)



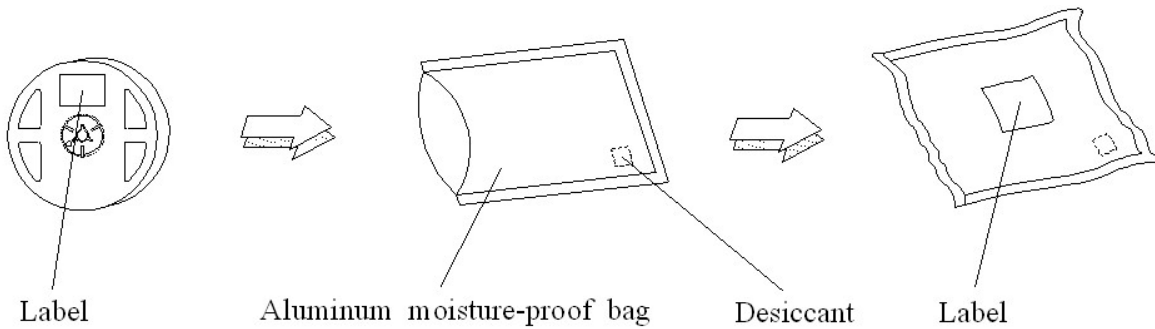
Temperature (°C)

Package Dimension



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process

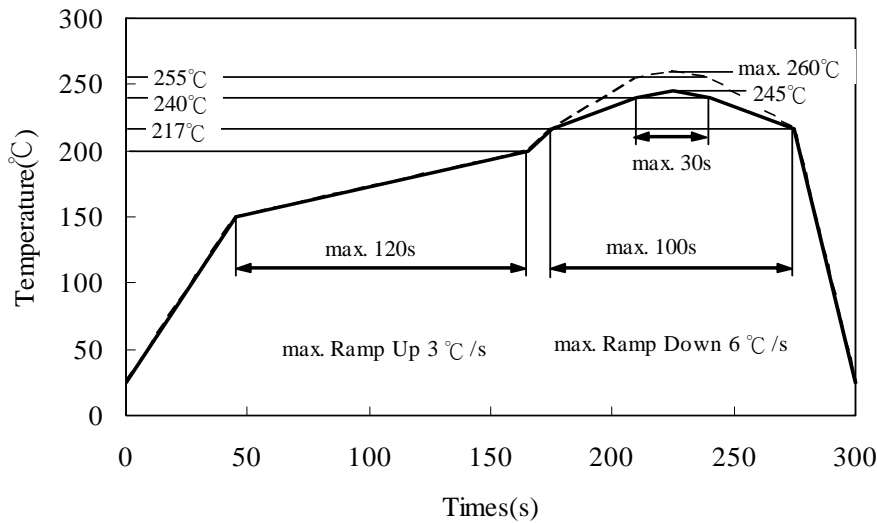


Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

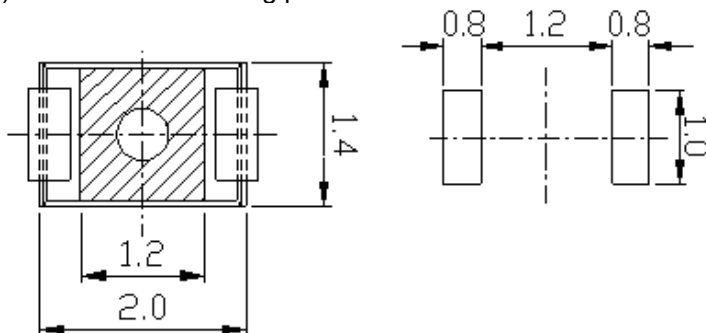
Precautions for Use

1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



(B) Recommend soldering pad



Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

3.1 Moisture proof bag should only be opened immediately prior to usage.

3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.

3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

Revision History

| Rev. | Modified date | File modified contents |
|------|---------------|-------------------------|
| 1 | 2010/02/10 | New Spec |
| 2 | 2010/03/30 | Preliminary |
| 3 | 2013/06/05 | Change the new template |
| | | |